



VMDSEMI

VUTL010R560NA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
100V	56mΩ@10V	27A
	69mΩ@4.5V	

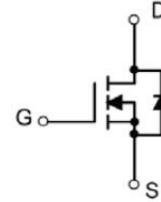


Figure 1 Symbol of VUTL010R560NA

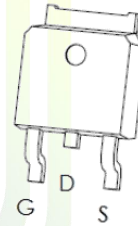
Features

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power switching application

Package Type



TO-252-2L

Figure 2 Package Type of VUTL010R560NA

Ordering Information

Product Name	Package
VUTL010R560NA	TO-252-2L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	27	A
Pulsed Drain Current ^{Note2}	I_{DM}	108	
Single Pulse Avalanche Energy ^{Note3}	I_{AS}	19	
Single Pulse Avalanche Energy ^{Note3}	E_{AS}	90	mJ
Total Power Dissipation ^{Note5}	P_D	41.7	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		50		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		3.0		°C/W



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.9	3.0	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(on)}$	$V_{GS}=10V, I_D=4A$		38	56	mΩ
		$V_{GS}=4.5V, I_D=4A$		41	69	
Forward transconductance ^{Note4}	g_{FS}	$V_{DS}=5V, I_D=4A$	10			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=45V$		2897		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		63.4		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		11.8		pF
Total Gate Charge	Q_g	$V_{DS}=50V$		54.5		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		8.0		
Gate-Drain Charge	Q_{gd}	$I_D=15A$		12.1		
Gate Resistance	R_g	$f=1MHz, \text{Open Drain}$		1.4		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$		7.5		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		3.5		
Turn-off Delay Time	$t_{d(off)}$	$R_L=5\Omega$		23		
Turn-off Fall Time	t_f	$R_G=3\Omega$		5.5		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=4A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Performance Characteristics

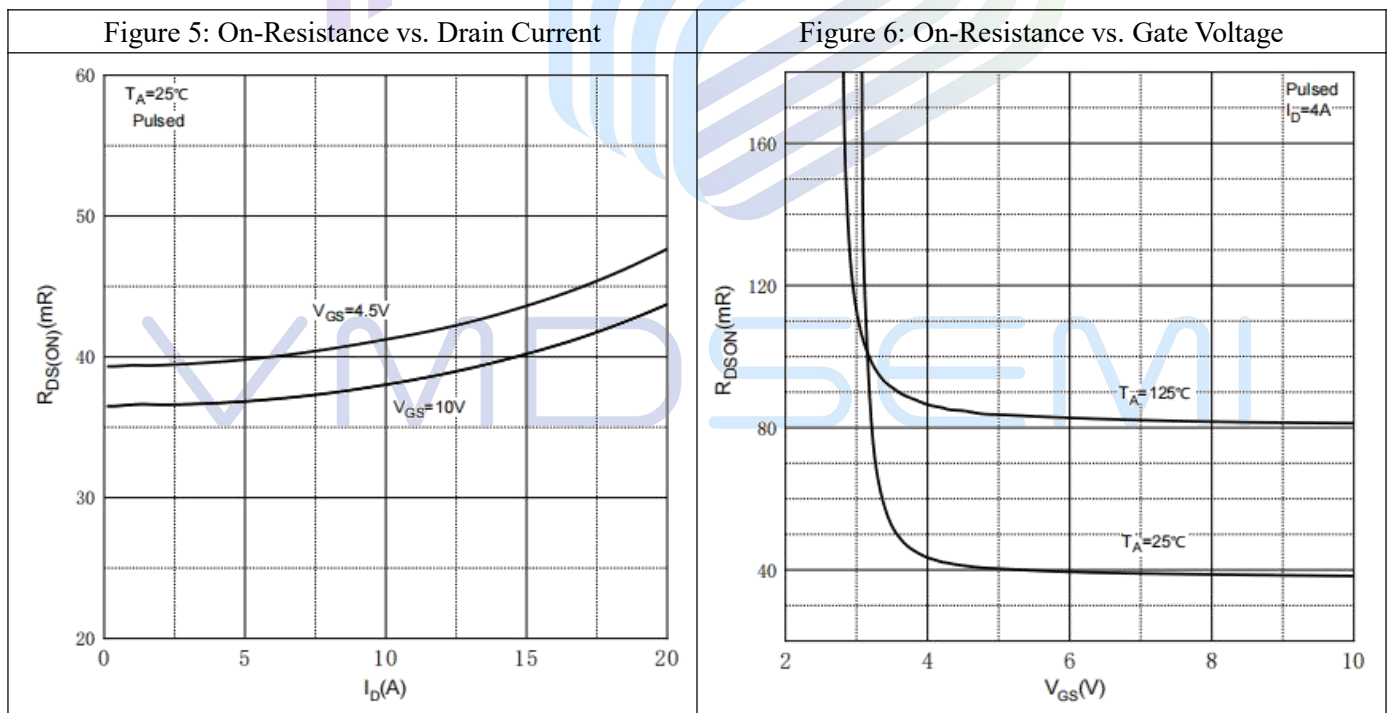
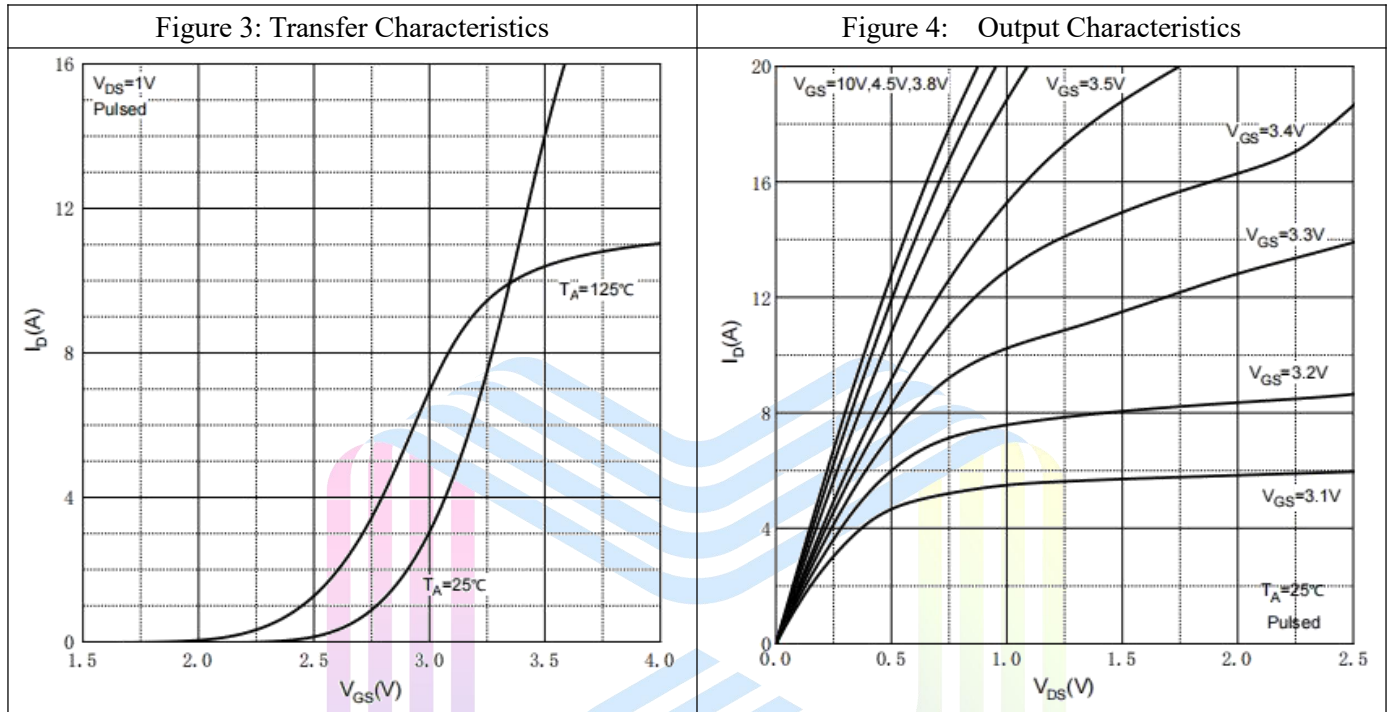


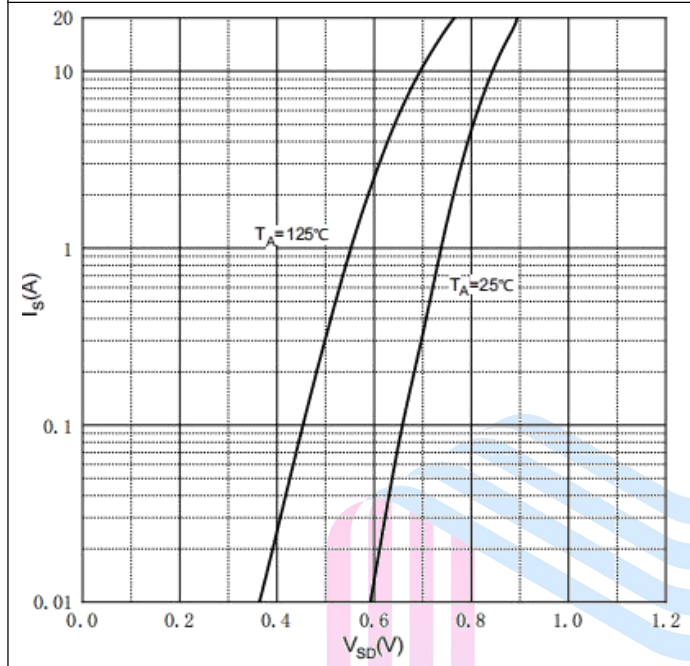
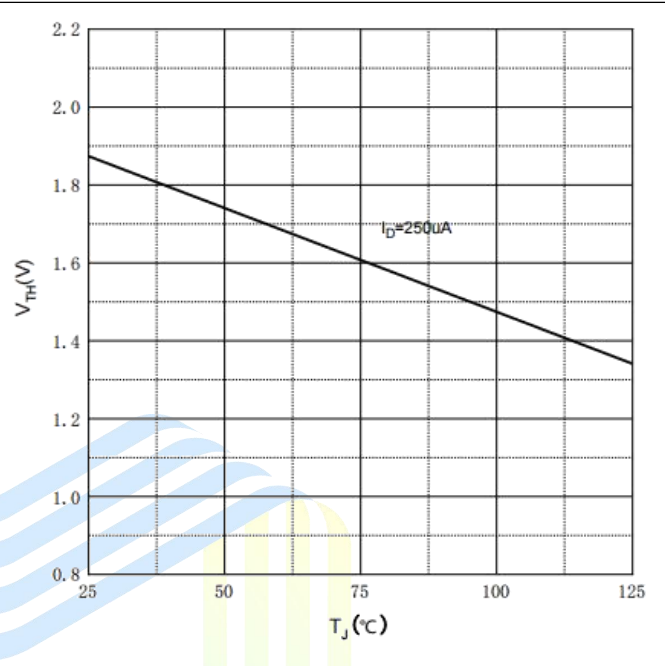
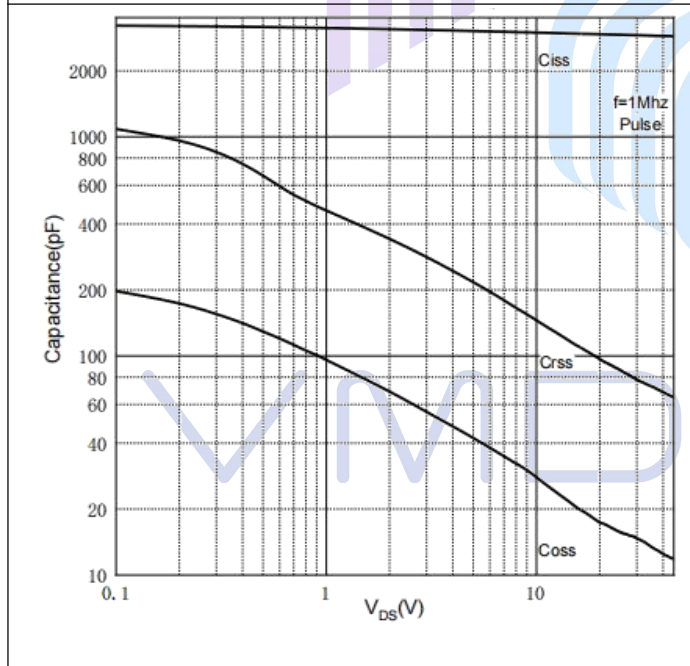
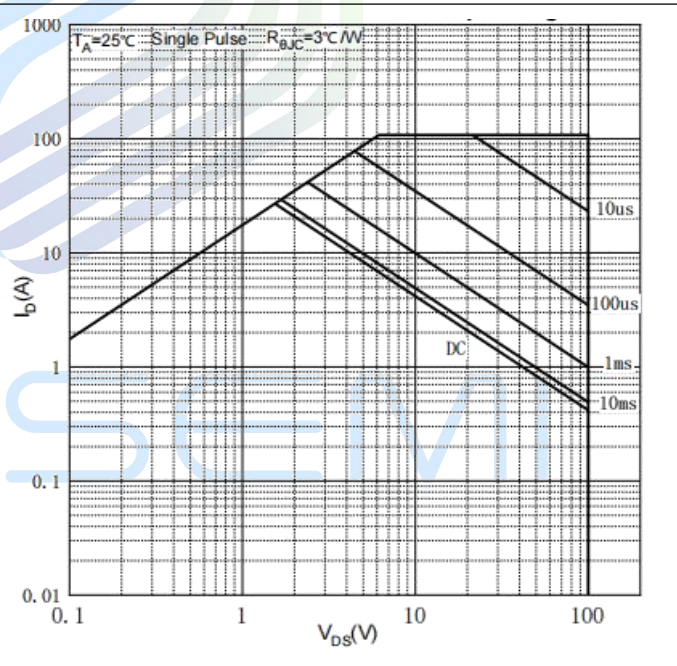
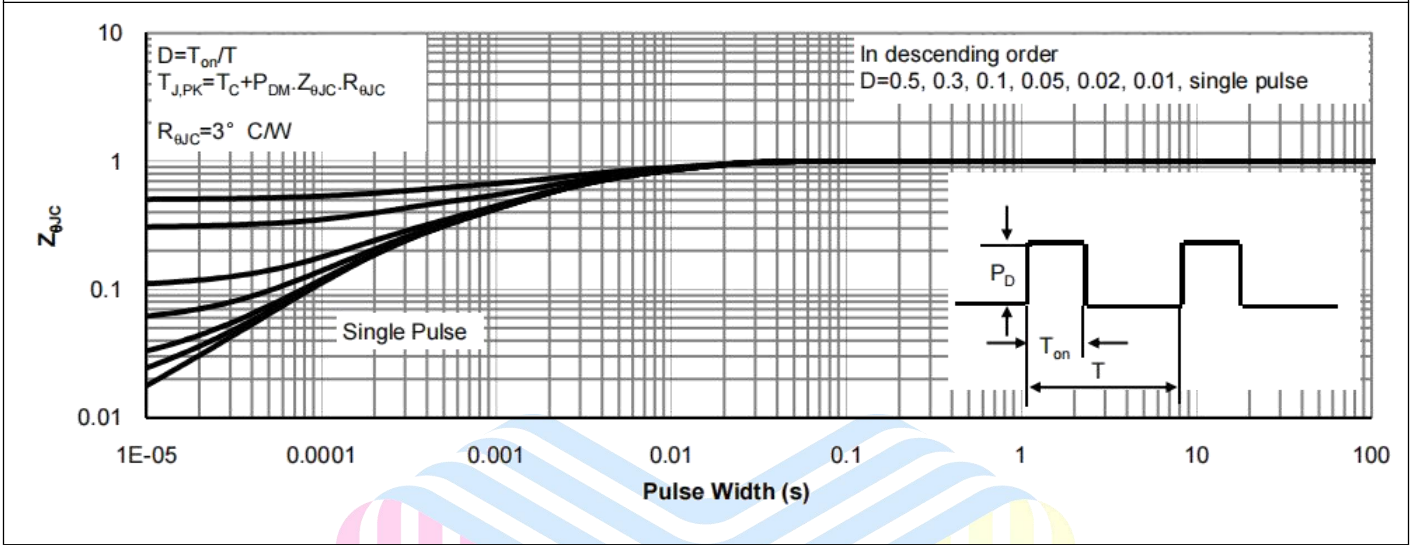
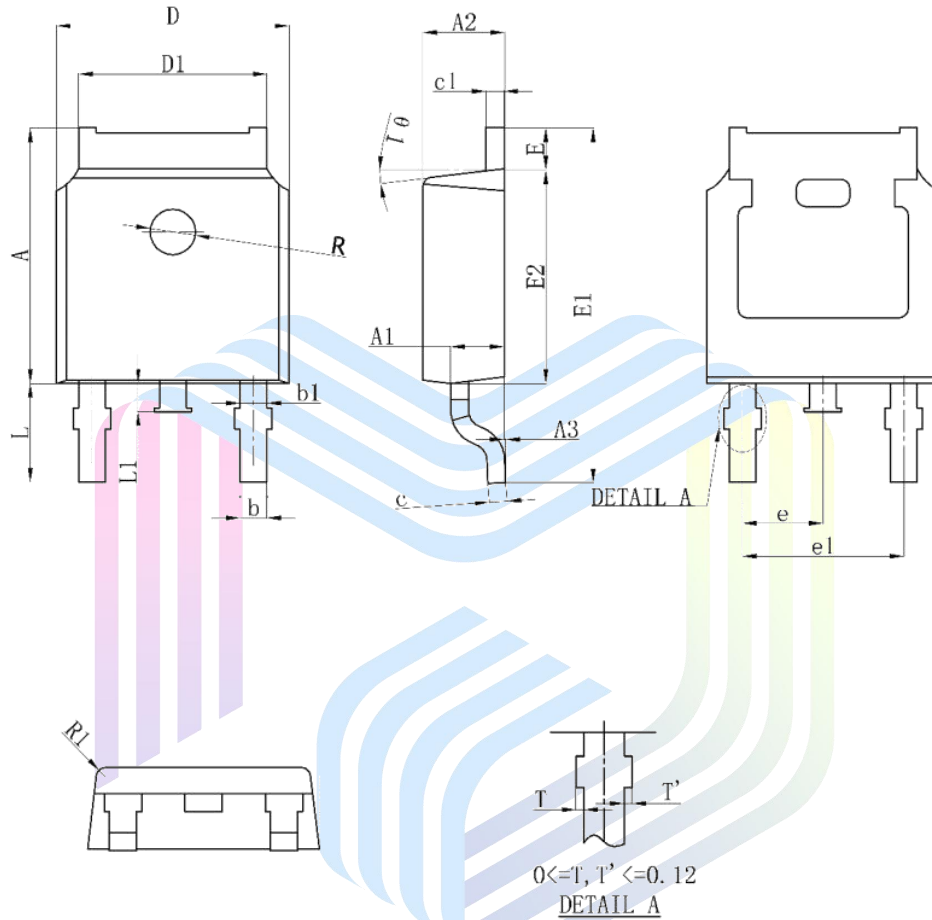
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance




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Mechanical Dimensions:
TO-252-2L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	7.050	7.150	0.278	0.281
A1	0.960	1.060	0.038	0.042
A2	2.200	2.400	0.087	0.094
A3	0.000	0.100	0.000	0.004
b	0.760REF		0.030REF	
b1	1.000REF		0.039REF	
c	0.508REF		0.020REF	
c1	0.508REF		0.020REF	
D	6.550	6.650	0.258	0.262
D1	5.100	5.460	0.201	0.215
E	0.950	1.050	0.037	0.041
E1	9.700	10.400	0.382	0.409
E2	6.000	6.200	0.236	0.244
e	2.286BSC		0.090BSC	
e1	4.572REF		0.180REF	
L	2.650	2.950	0.104	0.116
L1	0.700	0.900	0.028	0.035
θ1	7°REF		7°REF	
R	1.300REF		0.051REF	
R1	0.250REF		0.010REF	

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